

Power Schottky rectifier

Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Insulated package: TO-220FPAB
Insulating voltage = 2000 V DC
Capacitance = 12 pF
- Avalanche rated

Description

Dual center tap Schottky rectifier suited for switch mode power supply and high frequency DC to DC converters.

Packaged either in TO-220AB, TO-220FPAB, I²PAK, or D²PAK, this device is especially intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

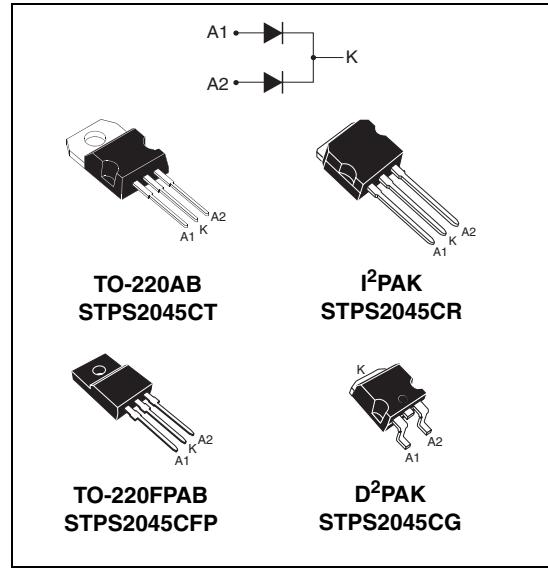


Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	2 x 10 A
V_{RRM}	45 V
$T_j(\text{max})$	175 °C
$V_F(\text{typ})$	0.57 V

1 Characteristics

Table 2. Absolute ratings (limiting values, per diode)

Symbol	Parameter				Value	Unit		
V_{RRM}	Repetitive peak reverse voltage				45	V		
$I_{F(RMS)}$	Forward rms current				30	A		
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220AB D ² PAK I ² PAK	$T_c = 155^\circ\text{C}$	Per diode	10	A		
		TO-220FPAB	$T_c = 125^\circ\text{C}$	Per device	20			
I_{FSM}	Surge non repetitive forward current		$t_p = 10\text{ ms sinusoidal}$		180	A		
P_{ARM}	Repetitive peak avalanche power		$t_p = 1\text{ }\mu\text{s } T_j = 25^\circ\text{C}$		4000	W		
T_{stg}	Storage temperature range				-65 to + 175	°C		
T_j	Maximum operating junction temperature ⁽¹⁾				175	°C		

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistances parameters

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220AB / D ² PAK / I ² PAK		Per diode	2.2
				Total	1.3
	TO-220FPAB			Per diode	4.5
				Total	3.5
$R_{th(c)}$	Coupling	TO-220AB / D ² PAK / I ² PAK		0.3	°C/W
		TO-220FPAB		Coupling	
					2.5

When the diodes 1 and 2 are used simultaneously :

$$T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

Table 4. Static electrical characteristics (per diode)

Symbol	Test conditions			Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			100	µA
		$T_j = 125^\circ\text{C}$			7	15	mA
$V_F^{(1)}$	Forward voltage drop	$T_j = 125^\circ\text{C}$	$I_F = 10\text{ A}$		0.5	0.57	V
		$T_j = 25^\circ\text{C}$	$I_F = 20\text{ A}$			0.84	
		$T_j = 125^\circ\text{C}$			0.65	0.72	

1. Pulse test : $t_p = 380\text{ }\mu\text{s}, \delta < 2\%$

To evaluate the conduction losses use the following equation : $P = 0.42 \times I_{F(AV)} + 0.015 I_{F(RMS)}^2$

Figure 1. Average forward power dissipation vs average forward current (per diode)

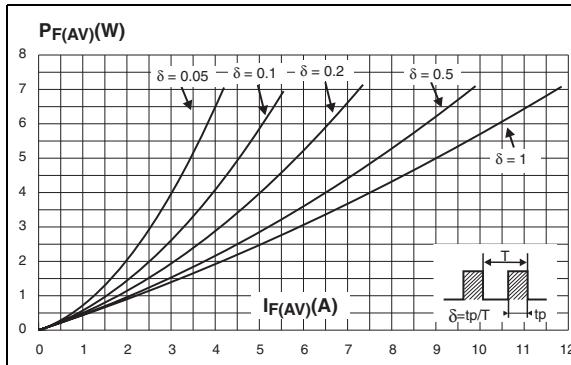


Figure 3. Normalized avalanche power derating vs pulse duration

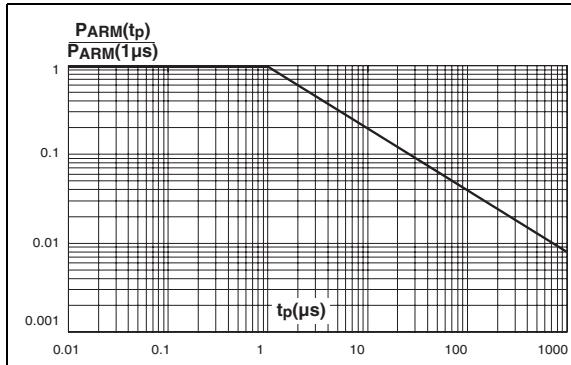


Figure 5. Non repetitive surge peak forward current vs overload duration (maximum values, per diode)

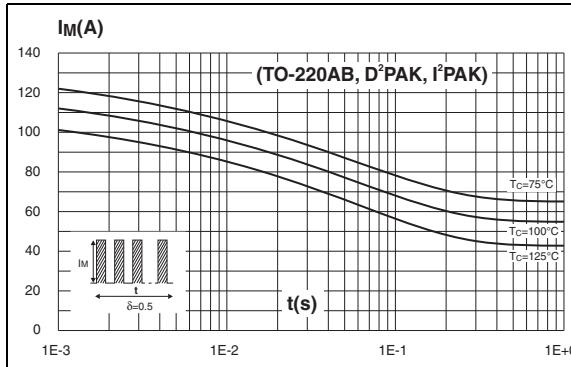


Figure 2. Average forward current vs ambient temperature ($\delta = 0.5$, per diode)

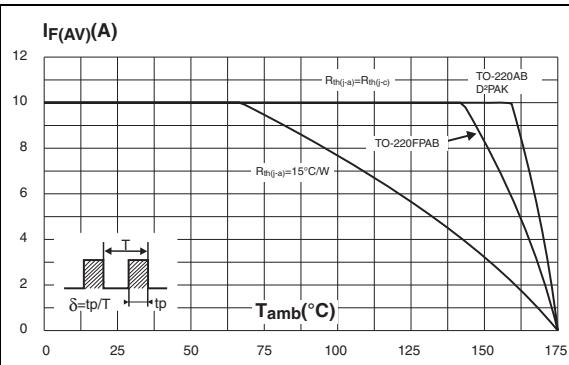


Figure 4. Normalized avalanche power derating vs junction temperature

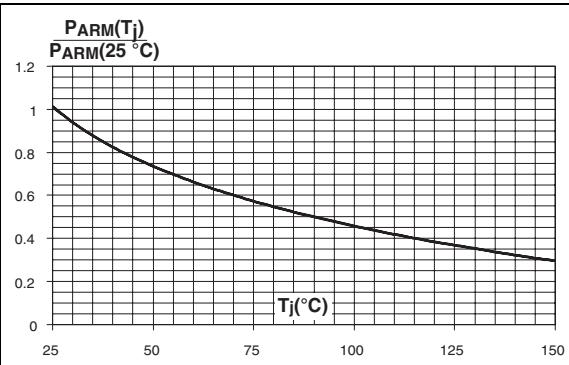


Figure 6. Non repetitive surge peak forward current vs overload duration (maximum values, per diode)

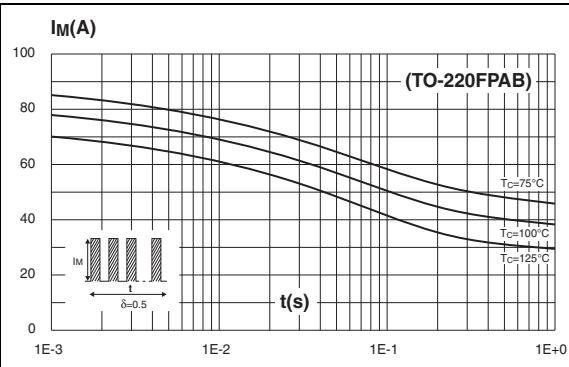


Figure 7. Relative variation of thermal impedance junction to ambient vs pulse duration

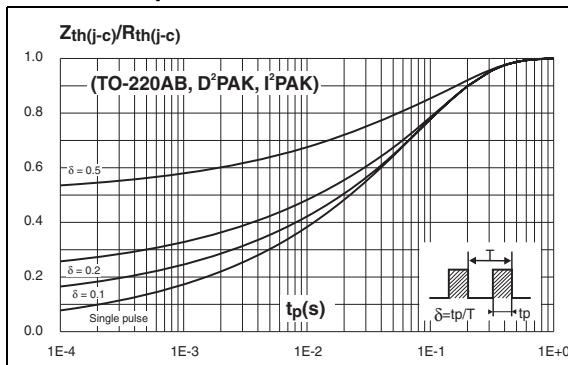


Figure 8. Relative variation of thermal impedance junction to ambient vs pulse duration (TO-220FPAB)

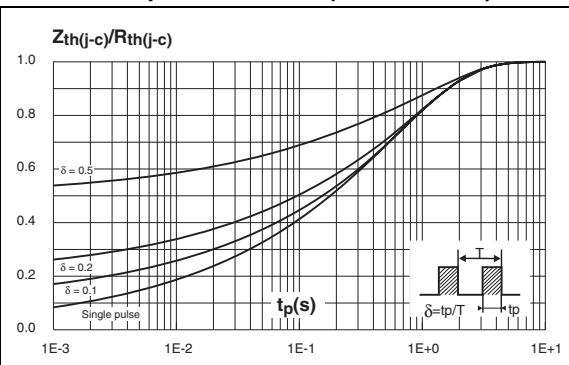


Figure 9. Reverse leakage current vs reverse voltage applied (typical values, per diode)

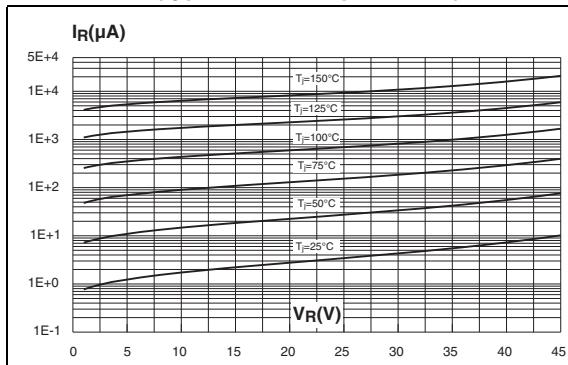


Figure 10. Junction capacitance vs reverse voltage applied (typical values, per diode)

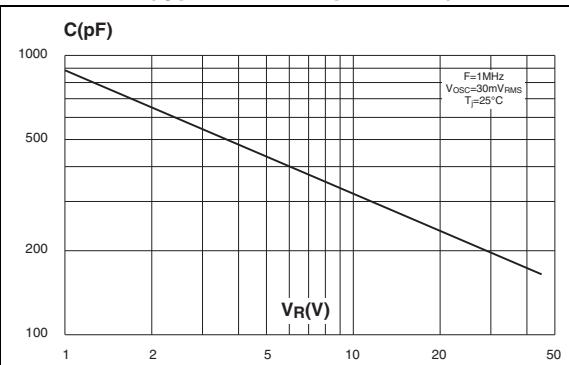


Figure 11. Forward voltage drop vs forward current (maximum values, per diode)

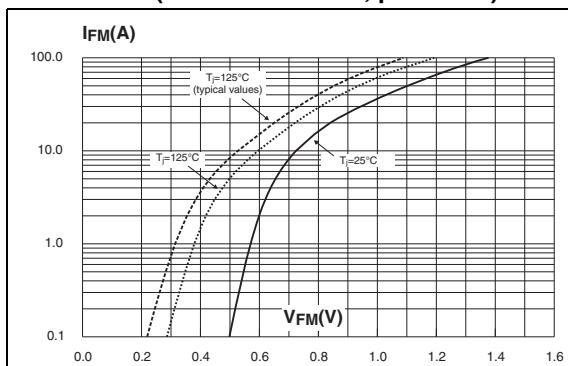
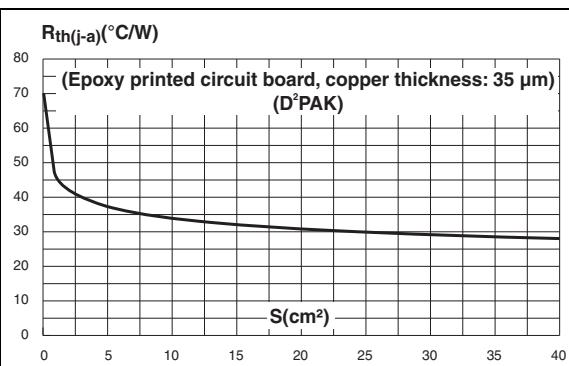


Figure 12. Thermal resistance junction to ambient vs copper surface under tab



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 N·m to 0.6 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

Table 5. D²PAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 13. Footprint (dimensions in mm)

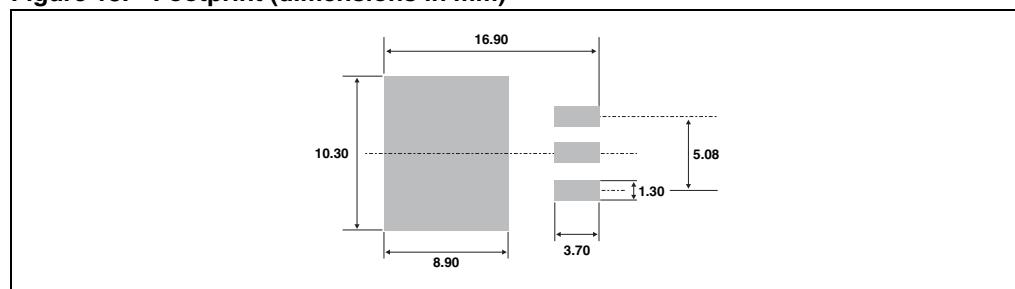
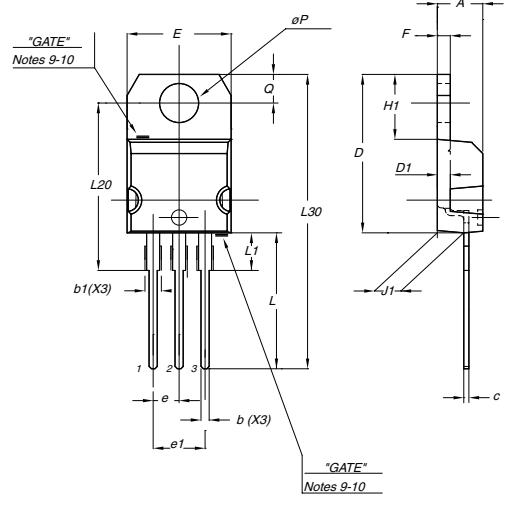
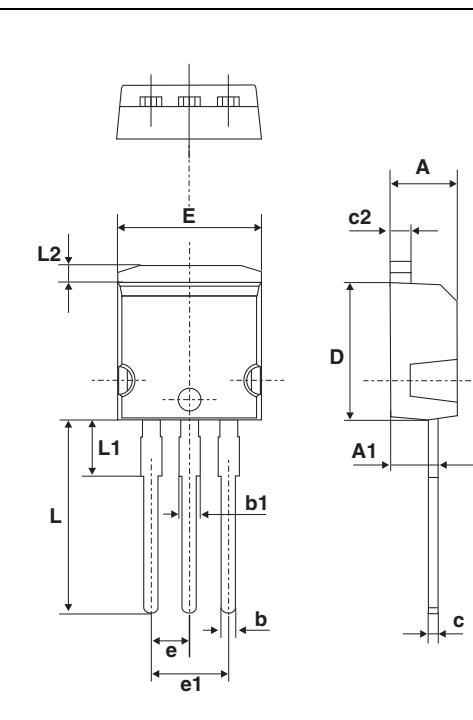


Table 6. TO-220AB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.17	0.18
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.045	0.067
c	0.48	0.70	0.019	0.027
D	15.25	15.75	0.60	0.62
D1	1.27 typ.		0.05 typ.	
E	10	10.40	0.39	0.41
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.19	0.20
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.24	0.26
J1	2.40	2.72	0.094	0.107
L	13	14	0.51	0.55
L1	3.50	3.93	0.137	0.154
L20	16.40 typ.		0.64 typ.	
L30	28.90 typ.		1.13 typ.	
øP	3.75	3.85	0.147	0.151
Q	2.65	2.95	0.104	0.116



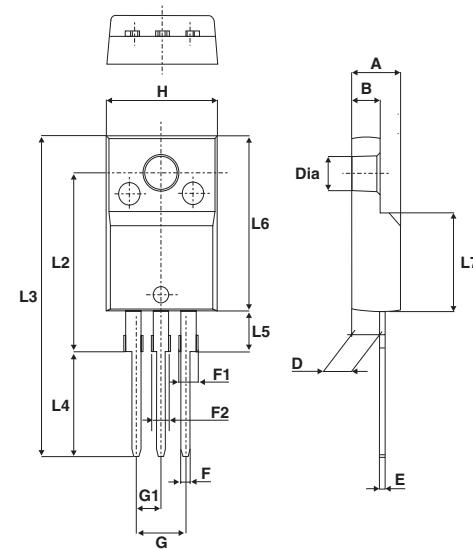
The technical drawing illustrates the physical dimensions of the TO-220AB package. It features two views: a front view showing the top lead profile with dimensions L20, L30, E, F, G, H1, D, J1, L, L1, øP, and Q; and a side view showing the height of the body (D) and the lead spacing (L). Callouts labeled "GATE" with notes 9-10 point to specific features on both views.

Table 7. I²PAK dimensions


Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.40	2.72	0.094	0.107
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.044	0.067
c	0.49	0.70	0.019	0.028
c2	1.23	1.32	0.048	0.052
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
E	10	10.40	0.394	0.409
L	13	14	0.512	0.551
L1	3.50	3.93	0.138	0.155
L2	1.27	1.40	0.050	0.055

Table 8. TO-220FPAB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126



The technical drawing illustrates the physical dimensions of the TO-220FPAB package. The top view shows the overall height (H) and lead spacing (L6). The side view provides detailed dimensions for the body height (L2), lead height (L3), lead thickness (L4), lead pitch (L5), lead length (L7), and the diameter of the lead tip (Dia.). Other labels include A, B, C, D, E, F, G, and G1, which correspond to specific feature locations on the package.

3 Ordering information

Table 9. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS2045CT	STPS2045CT	TO-220AB	2.23 g	50	Tube
STPS2045CR	STPS2045CR	I ² PAK	1.49 g	50	Tube
STPS2045CFP	STPS2045CFP	TO-220FPAB	2.0 g	50	Tube
STPS2045CG	STPS2045CG	D ² PAK	1.48 g	50	Tube
STPS2045CG-TR	STPS2045CG			1000	Tape and reel

4 Revision history

Table 10. Document revision history

Date	Revision	Changes
05-Oct-2004	4F	Last update
01-Dec-2004	5	Figure 16 (I ² PAK Package Mechanical Data): references b1 and b2 changed from 1.17mm to 1.70mm.
05-Feb-2010	6	Updated Table 2 (removed voltage). Updated ECOPACK statement. Updated Table 6.: TO-220AB dimensions .

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2010 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com